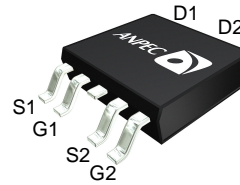


Dual Enhancement Mode MOSFET (N-and P-Channel)

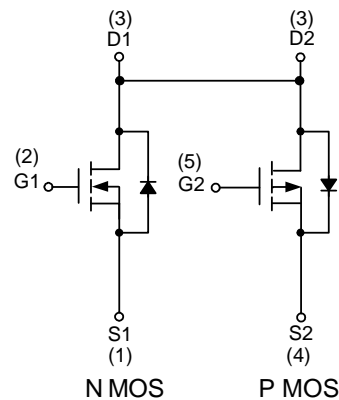
Features

- N-Channel
40V/7.5A,
 $R_{DS(ON)}=25m\Omega$ (typ.) @ $V_{GS}=10V$
 $R_{DS(ON)}=35m\Omega$ (typ.) @ $V_{GS}=4.5V$
- P-Channel
-40V/-6A,
 $R_{DS(ON)}=37m\Omega$ (typ.) @ $V_{GS}= -10V$
 $R_{DS(ON)}=49m\Omega$ (typ.) @ $V_{GS}=-4.5V$
- Super High Dense Cell Design
- Reliable and Rugged
- Lead Free and Green Devices Available (RoHS Compliant)

Pin Description



Top View of TO-252-4



Applications

- Power Management in LCD monitor/TV

Ordering and Marking Information

<p>APM4048D □□□-□□□</p> <p>Assembly Material Handling Code Temp. Range Package Code</p>	<p>Package Code U4 : TO-252-4 Operating Junction Temp. Range C : -55 to 150°C Handling Code TR : Tape & Reel Assembly Material L : Lead Free Device G : Halogen and Lead Free Device</p>
<p>APM4048D U4 : APM4048D XXXXX</p>	<p>XXXXX - Date Code</p>

Note: ANPEC lead-free products contain molding compounds/die attach materials and 100% matte tin plate termination finish; which are fully compliant with RoHS. ANPEC lead-free products meet or exceed the lead-free requirements of IPC/JEDEC J-STD-020C for MSL classification at lead-free peak reflow temperature. ANPEC defines "Green" to mean lead-free (RoHS compliant) and halogen free (Br or Cl does not exceed 900ppm by weight in homogeneous material and total of Br and Cl does not exceed 1500ppm by weight).

ANPEC reserves the right to make changes to improve reliability or manufacturability without notice, and advise customers to obtain the latest version of relevant information to verify before placing orders.

Absolute Maximum Ratings ($T_A = 25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	N Channel	P Channel	Unit	
V_{DSS}	Drain-Source Voltage	40	-40	V	
V_{GSS}	Gate-Source Voltage	± 20	± 20		
I_D^a	Continuous Drain Current	$T_C=25^\circ\text{C}$	7.5^b	-6^b	A
I_{DM}^a	Pulsed Drain Current	$T_C=25^\circ\text{C}$	30	-20	
I_S^a	Diode Continuous Forward Current	$T_C=25^\circ\text{C}$	7.5^b	-6^b	A
T_J	Maximum Junction Temperature	150		$^\circ\text{C}$	
T_{STG}	Storage Temperature Range	-55 to 150			
P_D	Power Dissipation	$T_C=25^\circ\text{C}$	25	W	
		$T_C=100^\circ\text{C}$	10		
$R_{\theta JC}$	Thermal Resistance-Junction to Case	5		$^\circ\text{C/W}$	
$R_{\theta JA}^a$	Thermal Resistance-Junction to Ambient	50		$^\circ\text{C/W}$	

Notes:

a : Surface Mounted on 1in^2 pad area, $t \leq 10\text{sec}$.

b : Current limited by bond wire.

Electrical Characteristics ($T_A = 25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Test Condition	APM4048DU4			Unit	
			Min.	Typ.	Max.		
Static Characteristics							
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}, I_{DS}=250\mu\text{A}$	N-Ch	40		V	
		$V_{GS}=0\text{V}, I_{DS}=-250\mu\text{A}$	P-Ch	-40			
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS}=32\text{V}, V_{GS}=0\text{V}$ $T_J=85^\circ\text{C}$	N-Ch		1	μA	
					30		
		$V_{DS}=-32\text{V}, V_{GS}=0\text{V}$ $T_J=85^\circ\text{C}$	P-Ch		-1		
					-30		
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_{DS}=250\mu\text{A}$	N-Ch	1.3	2.1	2.5	V
		$V_{DS}=V_{GS}, I_{DS}=-250\mu\text{A}$	P-Ch	-1.3	-1.9	-2.5	
I_{GSS}	Gate Leakage Current	$V_{GS}=\pm 20\text{V}, V_{DS}=0\text{V}$	N-Ch			± 100	nA
		$V_{GS}=\pm 20\text{V}, V_{DS}=0\text{V}$	P-Ch			± 100	
$R_{DS(ON)}^a$	Drain-Source On-State Resistance	$V_{GS}=10\text{V}, I_{DS}=7.5\text{A}$	N-Ch		25	33	$\text{m}\Omega$
		$V_{GS}=-10\text{V}, I_{DS}=-6\text{A}$	P-Ch		37	48	
		$V_{GS}=4.5\text{V}, I_{DS}=5\text{A}$	N-Ch		35	45	
		$V_{GS}=-4.5\text{V}, I_{DS}=-3.5\text{A}$	P-Ch		49	68	

Electrical Characteristics (Cont.) ($T_A = 25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Test Condition	APM4048DU4			Unit	
			Min.	Typ.	Max.		
Diode Characteristics							
V_{SD}^a	Diode Forward Voltage	$I_{SD}=2A, V_{GS}=0V$	N-Ch		0.8	1.1	V
		$I_{SD}=-2A, V_{GS}=0V$	P-Ch		-0.8	-1.1	
Dynamic Characteristics^b							
R_G	Gate Resistance	$V_{GS}=0V, V_{DS}=0V, F=1\text{MHz}$	N-Ch		1.5		Ω
			P-Ch		6.8		
C_{iss}	Input Capacitance	N-Channel $V_{GS}=0V,$ $V_{DS}=20V,$ Frequency=1.0MHz	N-Ch		950		pF
			P-Ch		1110		
C_{oss}	Output Capacitance	P-Channel $V_{GS}=0V,$ $V_{DS}=-20V,$ Frequency=1.0MHz	N-Ch		115		
			P-Ch		125		
C_{riss}	Reverse Transfer Capacitance	N-Channel $V_{GS}=0V,$ $V_{DS}=-20V,$ Frequency=1.0MHz	N-Ch		75		
			P-Ch		70		
$t_{d(ON)}$	Turn-on Delay Time	N-Channel $V_{DD}=20V, R_L=20\Omega,$ $I_{DS}=1A, V_{GEN}=10V,$ $R_G=6\Omega$	N-Ch		13	25	ns
			P-Ch		8	17	
t_r	Turn-on Rise Time	P-Channel $V_{DD}=-20V, R_L=20\Omega,$ $I_{DS}=-1A, V_{GEN}=-10V,$ $R_G=6\Omega$	N-Ch		10	19	
			P-Ch		12.5	24	
$t_{d(OFF)}$	Turn-off Delay Time	N-Channel $V_{DD}=20V, R_L=20\Omega,$ $I_{DS}=1A, V_{GEN}=10V,$ $R_G=6\Omega$	N-Ch		27	50	
			P-Ch		40	73	
t_f	Turn-off Fall Time	P-Channel $V_{DD}=-20V, R_L=20\Omega,$ $I_{DS}=-1A, V_{GEN}=-10V,$ $R_G=6\Omega$	N-Ch		5	10	
			P-Ch		15	28	
t_{rr}	Reverse Recovery Time	N-Channel $I_{SD}=7.5A, dI_{SD}/dt = 100A/\mu s$	N-Ch		20		ns
			P-Ch		19		
Q_{rr}	Reverse Recovery Charge	P-Channel $I_{SD}=-6A, dI_{SD}/dt = 100A/\mu s$	N-Ch		13		nC
			P-Ch		12		
Gate Charge Characteristics^b							
Q_g	Total Gate Charge	N-Channel $V_{DS}=20V, V_{GS}=10V,$ $I_{DS}=7.5A$	N-Ch		17.2	33	nC
			P-Ch		17.5	34.5	
Q_{gs}	Gate-Source Charge	P-Channel $V_{DS}=-20V, V_{GS}=-10V,$ $I_{DS}=-6A$	N-Ch		3.5		
			P-Ch		2.8		
Q_{gd}	Gate-Drain Charge		N-Ch		5.3		
			P-Ch		4		

Notes:

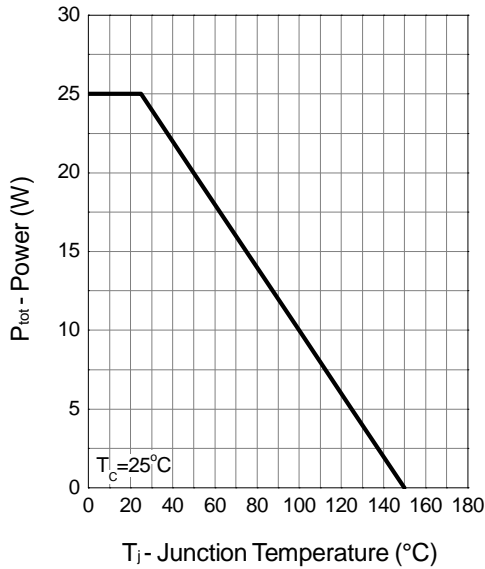
a : Pulse test ; pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$.

b : Guaranteed by design, not subject to production testing.

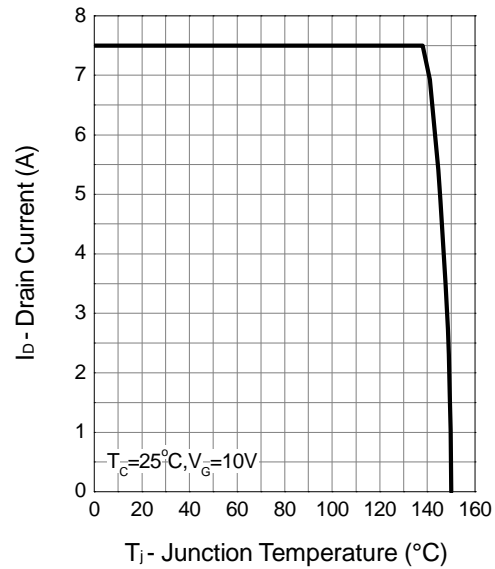
Typical Characteristics

N-Channel

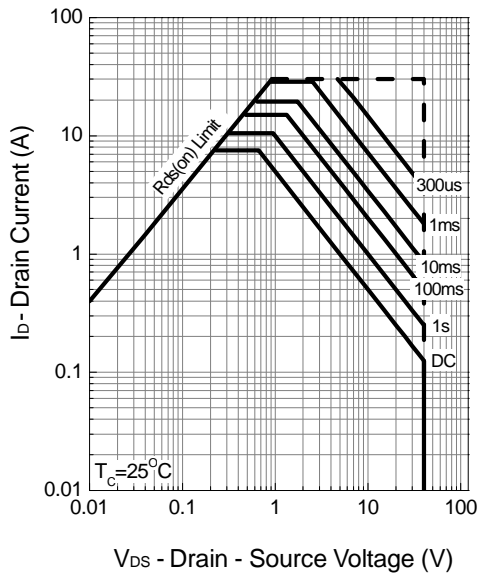
Power Dissipation



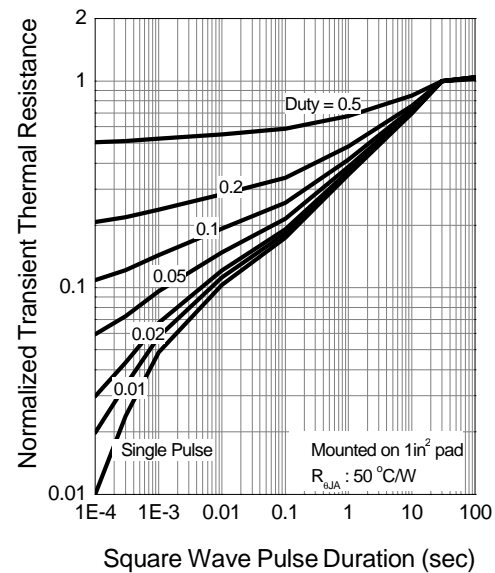
Drain Current



Safe Operation Area



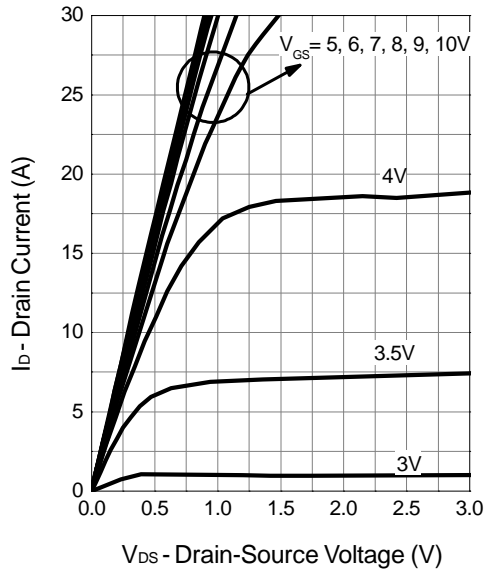
Thermal Transient Impedance



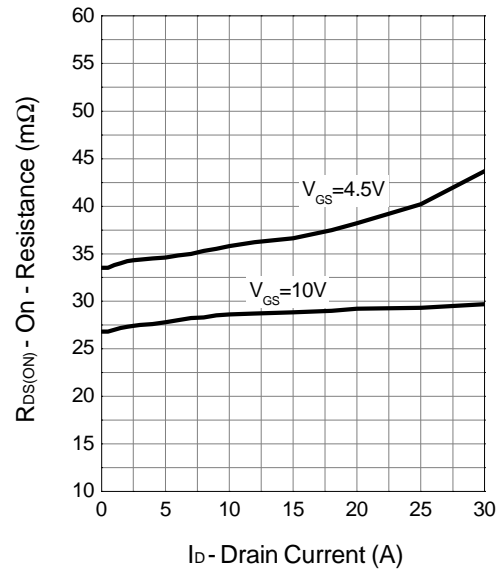
Typical Characteristics (Cont.)

N-Channel

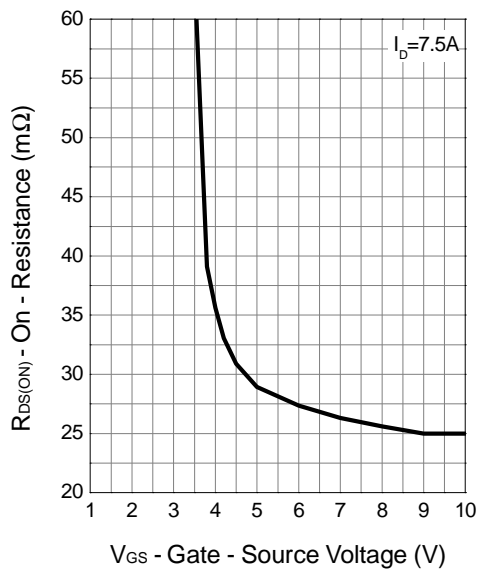
Output Characteristics



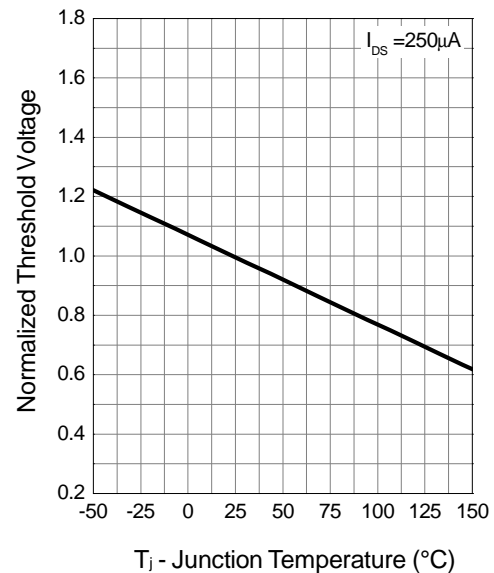
Drain-Source On Resistance



Gate-Source On Resistance



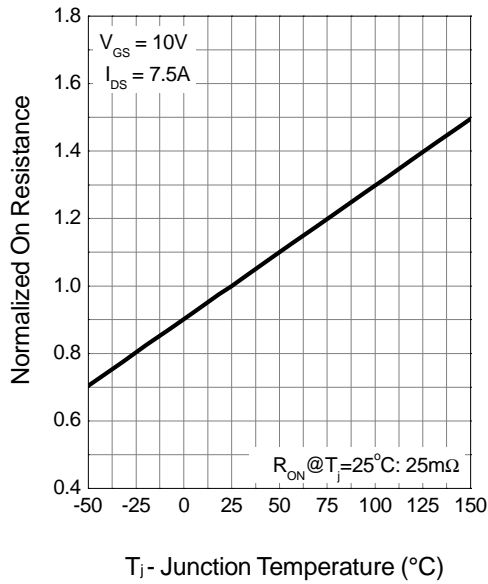
Gate Threshold Voltage



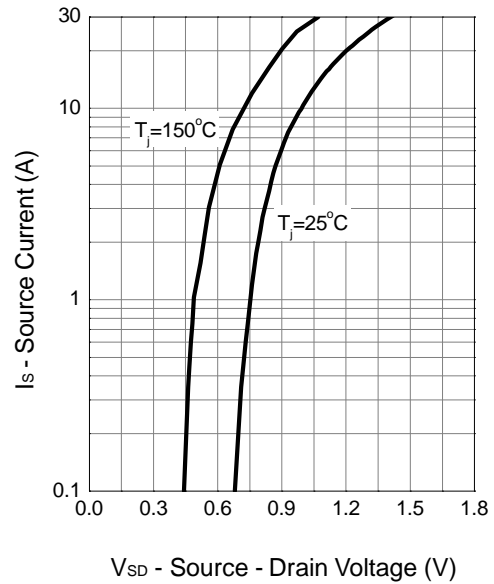
Typical Characteristics (Cont.)

N-Channel

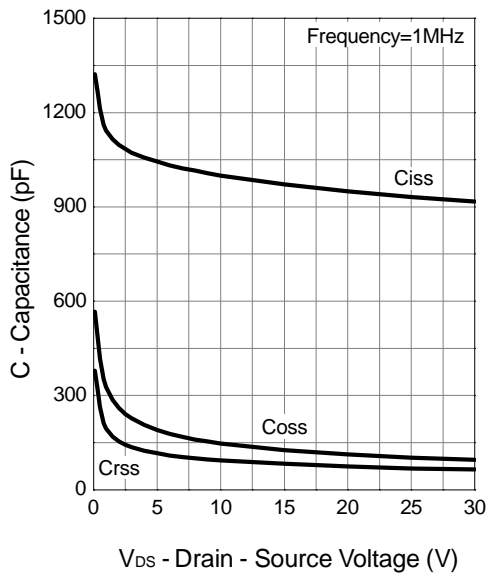
Drain-Source On Resistance



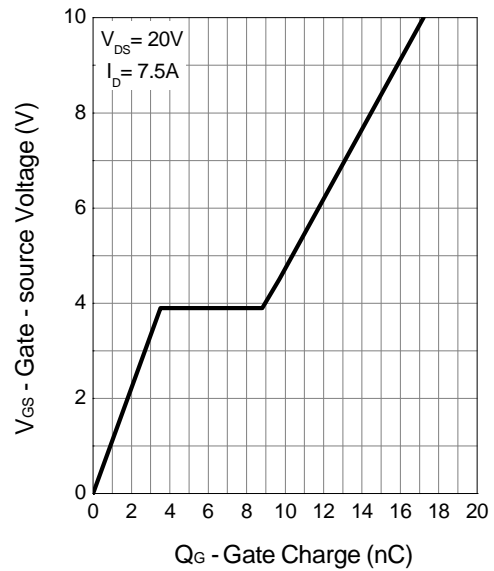
Source-Drain Diode Forward



Capacitance



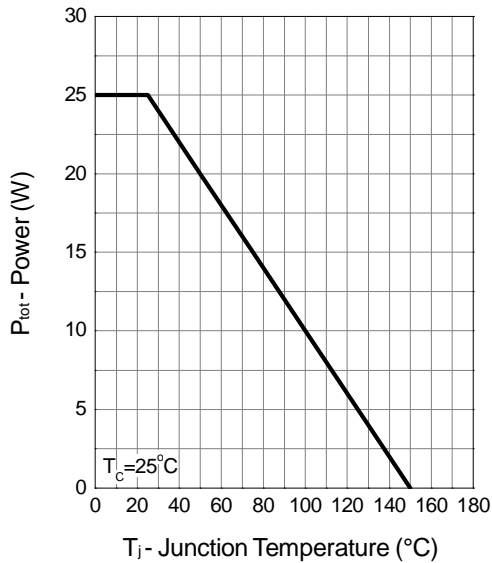
Gate Charge



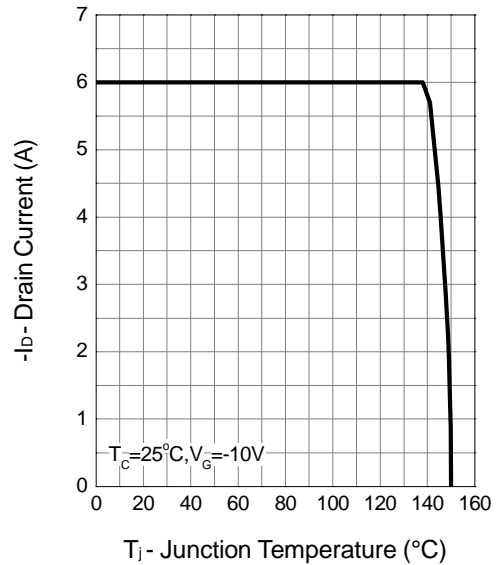
Typical Characteristics (Cont.)

P-Channel

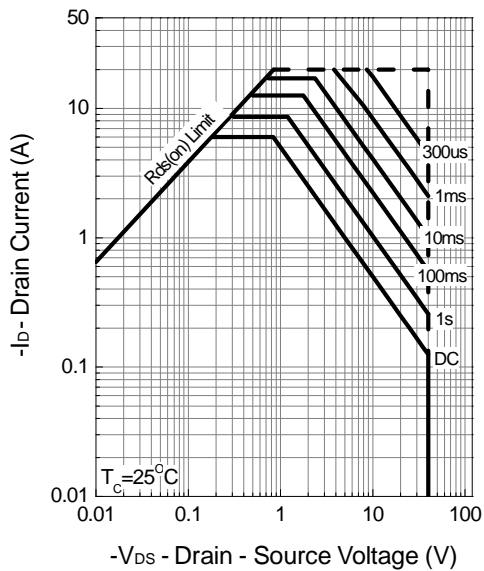
Power Dissipation



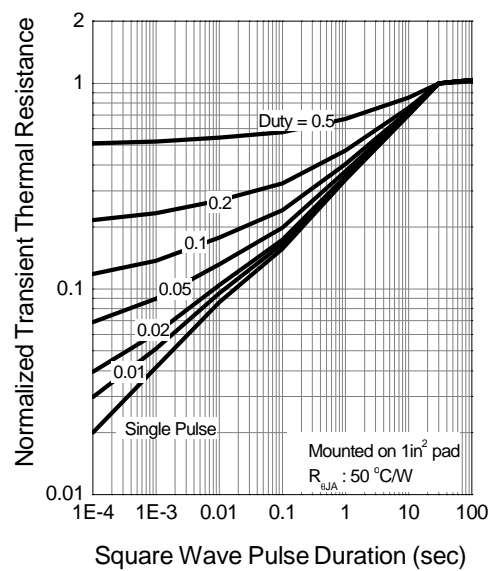
Drain Current



Safe Operation Area



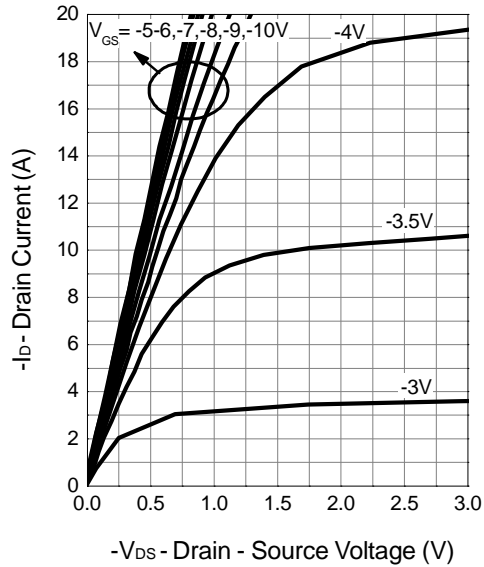
Thermal Transient Impedance



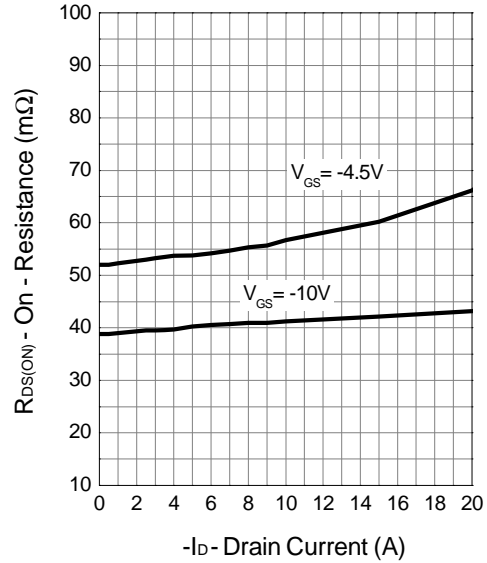
Typical Characteristics (Cont.)

P-Channel

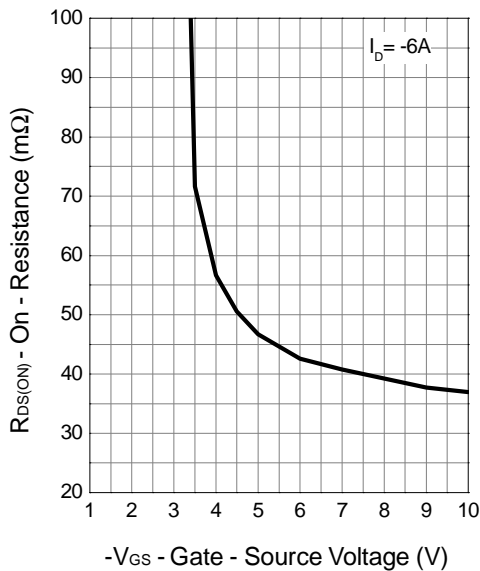
Output Characteristics



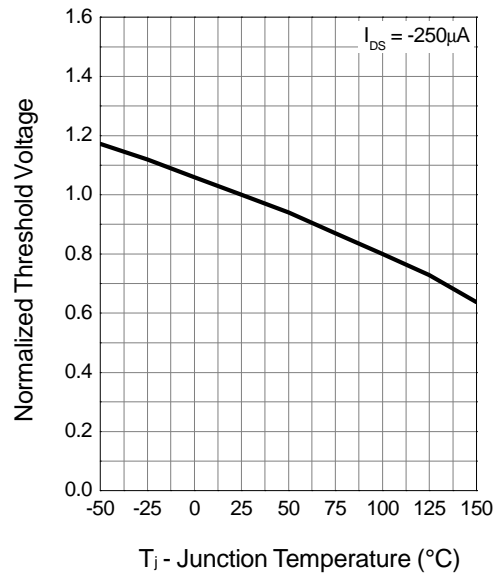
Drain-Source On Resistance



Gate-Source On Resistance

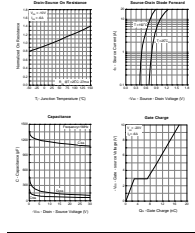


Gate Threshold Voltage



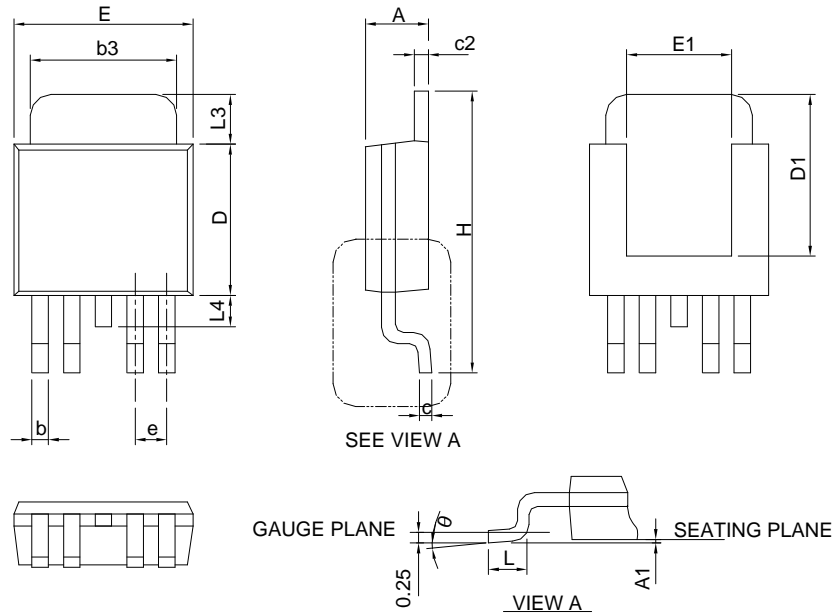
Typical Characteristics (Cont.)

Reference



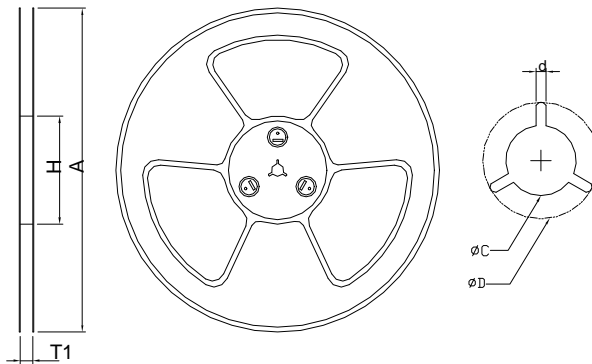
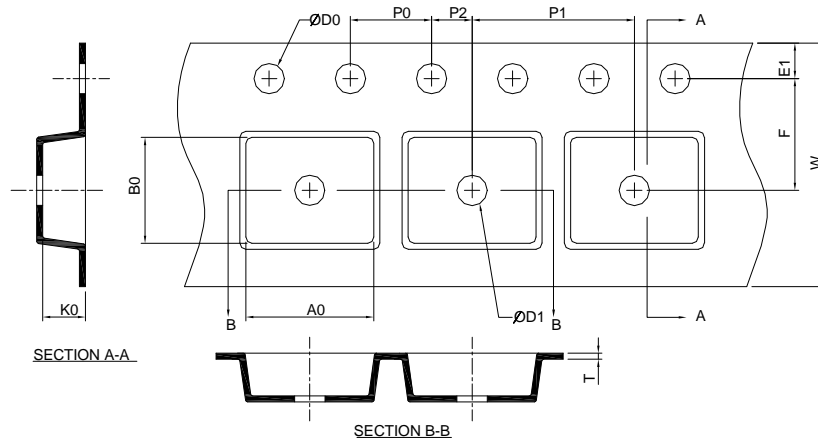
Package Information

TO-252-4



SYMBOL	TO-252-4			
	MILLIMETERS		INCHES	
	MIN.	MAX.	MIN.	MAX.
A	2.18	2.39	0.086	0.094
A1		0.13		0.005
b	0.50	0.71	0.020	0.028
b3	4.32	5.46	0.170	0.215
c	0.46	0.61	0.018	0.024
c2	0.46	0.89	0.018	0.035
D	5.33	6.22	0.210	0.245
D1	4.57	6.00	0.180	0.246
E	6.35	6.73	0.250	0.265
E1	3.81	6.00	0.150	0.246
e	1.27 BSC		0.050 BSC	
H	9.40	10.41	0.370	0.410
L	1.40	1.78	0.055	0.070
L3	0.89	2.03	0.035	0.080
L4		1.02		0.040
θ	0°	8°	0°	8°

Carrier Tape & Reel Dimensions



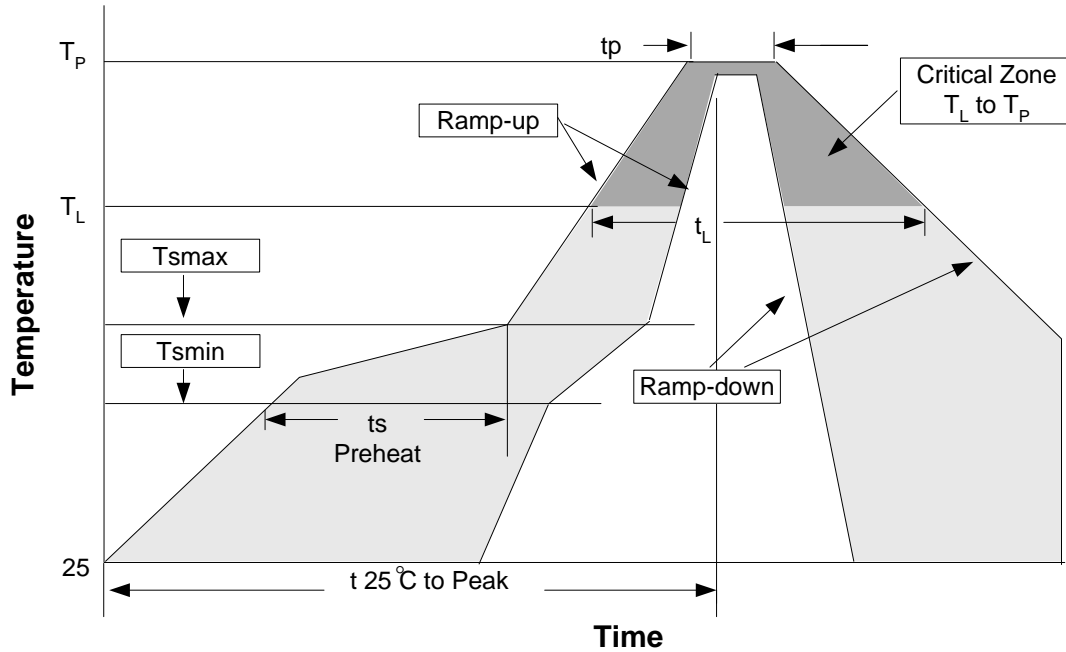
Application	A	H	T1	C	d	D	W	E1	F
TO-252	330.0 ± 2.00	50 MIN.	16.4+2.00 -0.00	13.0+0.50 -0.20	1.5 MIN.	20.2 MIN.	16.0 ± 0.30	1.75 ± 0.10	7.50 ± 0.05
	P0	P1	P2	D0	D1	T	A0	B0	K0
	4.0 ± 0.10	8.0 ± 0.10	2.0 ± 0.05	1.5+0.10 -0.00	1.5 MIN.	0.6+0.00 -0.40	6.80 ± 0.20	10.40 ± 0.20	2.50 ± 0.20

(mm)

Devices Per Unit

Package Type	Unit	Quantity
TO- 252	Tape & Reel	2500

Reflow Condition (IR/Convection or VPR Reflow)



Reliability Test Program

Test item	Method	Description
SOLDERABILITY	MIL-STD-883D-2003	245°C, 5 sec
HOLT	MIL-STD-883D-1005.7	1000 Hrs Bias @125°C
PCT	JESD-22-B, A102	168 Hrs, 100%RH, 121°C
TST	MIL-STD-883D-1011.9	-65°C~150°C, 200 Cycles

Classification Reflow Profiles

Profile Feature	Sn-Pb Eutectic Assembly	Pb-Free Assembly
Average ramp-up rate (T _L to T _P)	3°C/second max.	3°C/second max.
Preheat		
- Temperature Min (T _{smin})	100°C	150°C
- Temperature Max (T _{smax})	150°C	200°C
- Time (min to max) (t _s)	60-120 seconds	60-180 seconds
Time maintained above:		
- Temperature (T _L)	183°C	217°C
- Time (t _L)	60-150 seconds	60-150 seconds
Peak/Classification Temperature (T _P)	See table 1	See table 2
Time within 5°C of actual Peak Temperature (t _p)	10-30 seconds	20-40 seconds
Ramp-down Rate	6°C/second max.	6°C/second max.
Time 25°C to Peak Temperature	6 minutes max.	8 minutes max.

Note: All temperatures refer to topside of the package. Measured on the body surface.

Classification Reflow Profiles (Cont.)

Table 1. SnPb Eutectic Process – Package Peak Reflow Temperatures

Package Thickness	Volume mm ³ <350	Volume mm ³ ≥350
<2.5 mm	240 +0/-5°C	225 +0/-5°C
≥2.5 mm	225 +0/-5°C	225 +0/-5°C

Table 2. Pb-free Process – Package Classification Reflow Temperatures

Package Thickness	Volume mm ³ <350	Volume mm ³ 350-2000	Volume mm ³ >2000
<1.6 mm	260 +0°C*	260 +0°C*	260 +0°C*
1.6 mm – 2.5 mm	260 +0°C*	250 +0°C*	245 +0°C*
≥2.5 mm	250 +0°C*	245 +0°C*	245 +0°C*

*Tolerance: The device manufacturer/supplier **shall** assure process compatibility up to and including the stated classification temperature (this means Peak reflow temperature +0°C. For example 260°C+0°C) at the rated MSL level.

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